

Application No. 10/786,578
Amendment dated October 17, 2005
Reply to Office Action of July 8, 2005

Docket No. CM06657LL

Amendments to the Specification:

Please replace the paragraph beginning at line 22, page 2, and continuing to page 3, with the following amended paragraph:

In accordance with the present invention, there is provided herein a means of attaching a solid solder element (such as a solder ~~perform~~ preform) onto a contact surface of interest (such as a heat sink). The attachment means provided by the present invention overcomes alignment and registration issues that may interfere with good contact to microelectronic components (such as transistors), especially during the manufacturing/assembly process, such as reflow. For the purposes of this application the solid solder element may be a solder ~~perform~~ preform or other similar soldering interface attachment mechanism.

Please replace the paragraph beginning at line 5, page 6, with the following amended paragraph:

While the previous example has been described in terms of attaching a solid ~~solder~~ older element to a heat sink, the adhesive attachment mechanism of the present invention also has applications in shielding, grounding, and stiffening elements to parts placed on circuit boards and prior to reflow. The solid solder element may be planer or formed. The adhesive may be applied in continuous strips, individual nodules and may be cured at room temperature, elevated temperatures, with ultraviolet exposure, or other appropriate curing means. The attachment approach of the present invention provides location accuracy of a solid solder element and secondary piece part. The robust attachment is consistent part-to-part. The quality of the solder interface is consistent due to preservation of raw materials (no or low cure temperature and no added attachment pressure). Subsequent reflow of

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mechanical, electrical, or electro-mechanical components to the solderable substrate via the immobilized solid solder element provides improved alignment and fewer assembly failures in the overall stack up.